



Printed Circuit Boards
Interconnection Carriers

PRINTED CIRCUIT BOARDS

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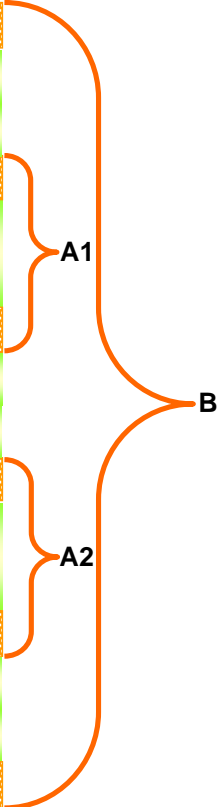







Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 157 FR4 35 L50.35 P06

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_157_FR4_35_L50.35_p06

Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper		
	60 μ	Prepreg		
	60 μ	Prepreg		
Layer-2	35 μ	Copper		
	500 μ	L-FR4		
Layer-3	35 μ	Copper		
	60 μ	Prepreg		
	60 μ	Prepreg		
Layer-4	35 μ	Copper		
	500 μ	L-FR4		
Layer-5	35 μ	Copper		
	60 μ	Prepreg		
	60 μ	Prepreg		
Layer-99	35 μ	Copper		